

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4959233

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YUKI SHINOHARA	06/26/2012
MIYAKO TERASAWA	06/28/2012
TOSHIYA HASEGAWA	07/26/2012
YOMEI OTANI	07/31/2012
NAOKI FUKINO	07/07/2012
TOSHINARI NAKAMURA	07/01/2012
RAJKUMAR WAGHMARE	07/30/2012
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SONY CORPORATION
<b>Street Address:</b>	1-7-1 KONAN, MINATO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	108-0075
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15971365
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(908)654-7866
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	SATURN 3.0-2857 CON
<b>NAME OF SUBMITTER:</b>	MELINDA C. CORMIER
<b>SIGNATURE:</b>	/Melinda C. Cormier/
<b>DATE SIGNED:</b>	05/14/2018

**Total Attachments: 6**

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**ASSIGNMENT**

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in  
INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD, PROGRAM, AND  
INFORMATION PROCESSING SYSTEM  
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **SONY CORPORATION**, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/565,961, Filing Date: August 3, 2012.

This assignment executed on the dates indicated below.

YUKI SHINOHARA

Name of first or sole inventor  
TOKYO, JAPAN

Residence of First or sole inventor

*Yuki Shinohara*  
Signature of first or sole inventor

Execution date of U.S. Patent Application

*June 26 2012*

Date of this assignment

MIYAKO TERASAWA

Name of second inventor  
TOKYO, JAPAN

Residence of second inventor

*Miyako Terasawa*  
Signature of second inventor

Execution date of U.S. Patent Application

*June 28, 2012*

Date of this assignment

TOSHIYA HASEGAWA

Name of third inventor  
TOKYO, JAPAN

Residence of third inventor

*Toshiya Hasegawa*  
Signature of third inventor

Execution date of U.S. Patent Application

*July 26 2012*  
Date of this assignment

ADDITIONAL INVENTOR(S)

YOMEI OTANI

Name of fourth inventor  
TOKYO, JAPAN

Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

July 31, 2012

NAOKI FUKINO

Name of fifth inventor  
TOKYO, JAPAN

Residence of fifth inventor

Signature of fifth inventor

Execution date of U.S. Patent Application

Date of this assignment

TOSHINARI NAKAMURA

Name of sixth inventor  
TOKYO, JAPAN

Residence of sixth inventor

Signature of sixth inventor

Execution date of U.S. Patent Application

Date of this assignment

RAJKUMAR WAGHMARE

Name of seventh inventor  
KANAGAWA, JAPAN

Residence of seventh inventor

Signature of seventh inventor

Execution date of U.S. Patent Application

Date of this assignment

July 30, 2012

Name of eighth inventor

Residence of eighth inventor

Signature of eighth inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of ninth inventor

Residence of ninth inventor

Signature of ninth inventor

Execution date of U.S. Patent Application

Date of this assignment

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MIYAKO TERASAWA

Name of second inventor  
TOKYO, JAPAN

Residence of second inventor

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Signature of second inventor

Date of this assignment

TOSHIYA HASEGAWA

Name of third inventor  
TOKYO, JAPAN

Residence of third inventor

Execution date of U.S. Patent Application

Signature of third inventor

Date of this assignment

ADDITIONAL INVENTOR(S)

YOMEI OTANI

Name of fourth inventor

TOKYO, JAPAN

Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

NAOKI FUKINO

Name of fifth inventor

TOKYO, JAPAN

Residence of fifth inventor

*Naoki Fukino*  
Signature of fifth inventor

Execution date of U.S. Patent Application

*07/07/2012*  
Date of this assignment

TOSHINARI NAKAMURA

Name of sixth inventor

TOKYO, JAPAN

Residence of sixth inventor

Signature of sixth inventor

Execution date of U.S. Patent Application

Date of this assignment

RAJKUMAR WAGHMARE

Name of seventh inventor

KANAGAWA, JAPAN

Residence of seventh inventor

Signature of seventh inventor

Execution date of U.S. Patent Application

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Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

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Name of ninth inventor

Execution date of U.S. Patent Application

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TOKYO, JAPAN

Residence of First or sole inventor

Execution date of U.S. Patent Application

Signature of first or sole inventor

Date of this assignment

MIYAKO TERASAWA

Name of second inventor  
TOKYO, JAPAN

Residence of second inventor

Execution date of U.S. Patent Application

Signature of second inventor

Date of this assignment

TOSHIYA HASEGAWA

Name of third inventor  
TOKYO, JAPAN

Residence of third inventor

Execution date of U.S. Patent Application

Signature of third inventor

Date of this assignment

ADDITIONAL INVENTOR(S)

YOMEI OTANI

Name of fourth inventor  
TOKYO, JAPAN

Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

NAOKI FUKINO

Name of fifth inventor  
TOKYO, JAPAN

Residence of fifth inventor

Signature of fifth inventor

Execution date of U.S. Patent Application

Date of this assignment

TOSHINARI NAKAMURA

Name of sixth inventor  
TOKYO, JAPAN

Residence of sixth inventor

~~Signature of sixth inventor~~ *Toshinari Nakamura*

Execution date of U.S. Patent Application

*July 1, 2012*  
~~1/19/2012~~  
Date of this assignment *July 1, 2012 T.N*

RAJKUMAR WAGHMARE

Name of seventh inventor  
KANAGAWA, JAPAN

Residence of seventh inventor

Signature of seventh inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment